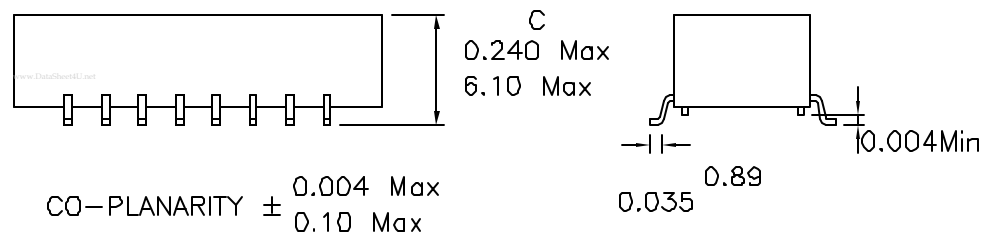
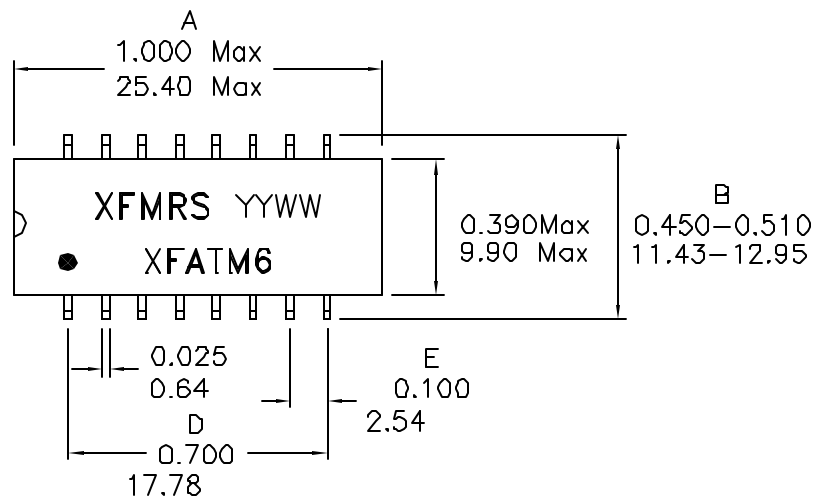
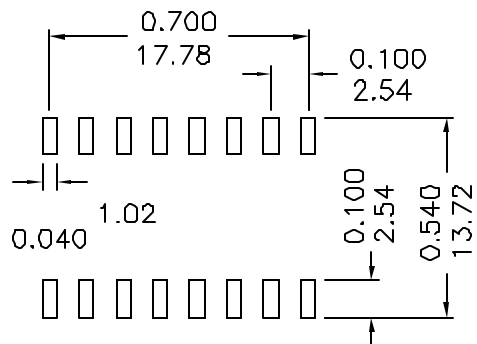


1. Mechanical Dimensions:



CO-PLANARITY \pm 0.004 Max
0.10 Max

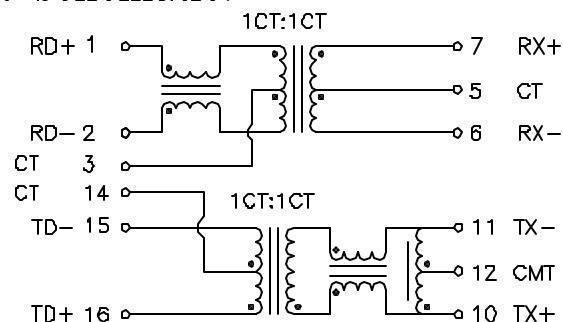


SUGGESTED FOOTPRINT

Notes:

- Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
- Flammability: UL94V-0
- ASTM oxygen index: > 28%
- Insulation System: Class F 155°C, UL file E151556
- Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
- Storage Temperature Range: -55°C to +125°C
- Aqueous wash compatible
- SMD Lead Coplanarity: $\pm 0.004^*$ (0.102mm)
- Moisture Sensitivity: Level 3
- Electrical and mechanical specifications 100% tested
- RoHS Compliant Component

2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms
 CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA
 Rise Time (10-90%): 4.0ns Typ
 Insertion Loss (100KHz-100MHz): -1.0dB Max
 Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz
 -20dB -20dB -18dB -14dB (Min)
 CMRR: 30MHz 60MHz 100MHz
 -42dB -36dB -33dB (Min)
 CROSSTALK: 30MHz 60MHz 100MHz
 -50dB -40dB -40dB (Min)

DOC. REV. F/15

PROPRIETARY

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XFMRs Inc. www.XFMRs.com		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ± 0.010 Inch Dimensions in Inch/mm		P/N: XFATM6	REV. F
		DWN. 罗振江	Aug-15-05
SCALE 2:1 SHT 1 OF 1		CHK. 廖玉坤	Aug-15-05
		APP. BW	Aug-15-05